




<b>PCN Number:</b>	20220818002.1		<b>PCN Date:</b>	August 18, 2022												
<b>Title:</b>	Qualification of TIPI as an alternate Assembly site for select devices															
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services													
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Nov 16, 2022	<b>Sample Requests accepted until:</b>	Sept 18, 2022													
<b>*Sample requests received after Sept 18, 2022 will not be supported.</b>																
<b>Change Type:</b>																
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site											
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material											
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process											
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site											
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials											
				<input type="checkbox"/>	Wafer Fab Process											
<b>PCN Details</b>																
<b>Description of Change:</b>																
Texas Instruments Incorporated is announcing the qualification of TIPI as an additional Assembly site for the select devices listed below. Construction differences are noted below:																
<table border="1"> <thead> <tr> <th>What</th> <th>Hana</th> <th>JCET</th> <th>TIPI</th> </tr> </thead> <tbody> <tr> <td><b>Mold Compound</b></td> <td>SID#450214</td> <td>S#11102000380 9</td> <td><b>4222198</b></td> </tr> <tr> <td><b>Mount Compound</b></td> <td>SID#400194</td> <td>S#12040200160 0</td> <td><b>4226215</b></td> </tr> </tbody> </table>					What	Hana	JCET	TIPI	<b>Mold Compound</b>	SID#450214	S#11102000380 9	<b>4222198</b>	<b>Mount Compound</b>	SID#400194	S#12040200160 0	<b>4226215</b>
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<b>Mount Compound</b>	SID#400194	S#12040200160 0	<b>4226215</b>													
<b>Reason for Change:</b>																
Supply continuity																
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>																
None																
<b>Impact on Environmental Ratings</b>																
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																
<b>RoHS</b>	<b>REACH</b>	<b>Green Status</b>	<b>IEC 62474</b>													
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change													
<b>Changes to product identification resulting from this PCN:</b>																
<b>Assembly Site</b>	<b>Assembly Site Origin (22L)</b>	<b>Assembly Country Code (23L)</b>	<b>Assembly City</b>													
Hana	HNT	THA	Ayutthaya													
JCET	JCE	CHN	Jiangyin													
<b>TIPI</b>	<b>PHI</b>	<b>PHL</b>	<b>Baguio City</b>													
Sample product shipping label (not actual product label)																



MADE IN: Malaysia  
2DC: 20:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L)T0:1750

  
G4
 

(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS

**Product Affected:**

TPD2E1B06DRLR	TPD4E1B06DRLR	
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TI Information  
Selective Disclosure

**Qualification Results**  
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPD2E1B06DRLR	QBS Package Reference: TMP102AIDRLR
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	3/231/0
HTOL	High Temp Operating Life, 125C	1000 Hours	-	1/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	1/77/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass
PD	Physical Dimensions	(per mechanical drawing)	3/15/0	-
SD	Solderability	Pb free	3/66/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	3/231/0	3/231/0
VM	Visual / Mechanical	(per mfg. Site specification)	3/984/0	-
WBP	Bond Pull	Wires	3/228/0	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0	3/228/0

- QBS: Qual By Similarity
  - Qual Device TPD2E1B06DRLR is qualified at LEVEL1-260C
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**  
Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20210618-140599

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
WW Change Management Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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